

What is claimed is:

- 1 1. Land Grid Array structure comprising,
2 a flex film interposer for providing a Land Grid Array (LGA)
3 electrical connection between a Multi-Chip Module (MCM) and
4 the next level of integration such of a Land Grid Array
5 system and also provides means for implementing a desired
6 Engineering Change (EC) and means for decoupling power to
7 ground in the Land Grid Array structure to minimize
8 switching activity effects on the Land Grid Array system.

- 1 2. A method of making an engineering change for a Land Grid
2 Array structure, comprising the steps of:
3 providing a system board for the Land Grid Array
4 structure,
5 providing a module for said Land Grid Array structure;
6 providing a flex film interposer having multiple
7 conductive layers between said system board and said module,
8 said flex film interposer having a plurality of plated
9 through holes in the flex film which provide a plurality of
10 metallic interfaces for interconnection between a multi-chip
11 module chip carriers and the next level of intergration of a
12 Land Grid Array.

- 1 3. A method of making an engineering change for a system
2 board structure, comprising the steps of:
3 providing a system board,
4 providing a plurality of chip carrier modules for said
5 the next level of integration provided by a system board, at
6 least one of which plurality of chip carrier modules has a
7 functional connection that could be desireably changed,
8 and providing an interface between the system board and
9 the chip carrier modules that fulfills a desired engineering
10 change by physically changing an original connection to